

FDG6324L Rev.D

Sumbol	Parameter	Conditions	Min	Tum	Мах	Units
Symbol	Farameter	Conditions	IVIIII	Тур	wax	Units
OFF CHAP	RACTERISTICS					
I _{FL}	Forward Leakage Current	$V_{IN} = 20 \text{ V}, V_{ON/OFF} = 0 \text{ V}$			1	μA
ON CHAR	ACTERISTICS (Note 3)					
V _{DROP}	Conduction Voltage Drop	$V_{IN} = 12~V,~~V_{ON/OFF} = 3.3~V,~I_L = 0.36~A$		0.14	0.2	V
		$V_{IN} = 5 \text{ V}, V_{ON/OFF} = 3.3 \text{ V}, I_{L} = 0.27 \text{ A}$		0.16	0.2	
R _(ON)	Q ₂ - Static On-Resistance	$V_{GS} = -12 \text{ V}, \ \text{I}_{D} = -0.6 \text{ A}$		0.37	0.55	Ω
		$V_{GS} = -5 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$		0.58	0.75	
I _L	Load Current	V_{DROP} = 0.2 V, V_{IN} = 12 V, $V_{\text{ON/OFF}}$ = 3.3 V	0.36			А
		V _{DROP} = 0.2 V, V _{IN} = 5 V, V _{ON/OFF} = 3.3 V	0.27]

Notes:

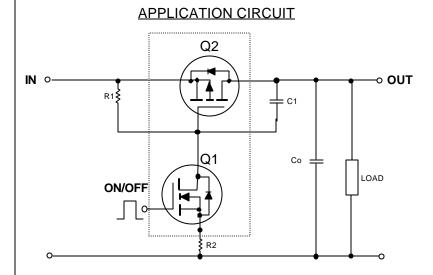
1. Range of V_{in} can be up to 25V, but R₁ and R₂ must be scaled such that V_{GS} of Q2 does not exceed -20V.

2. R_{8.4} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8.6} is

guaranteed by design while R_{BCA} is determined by the user's board design. Thermal ratings based on minimum mounting pad.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2.0%

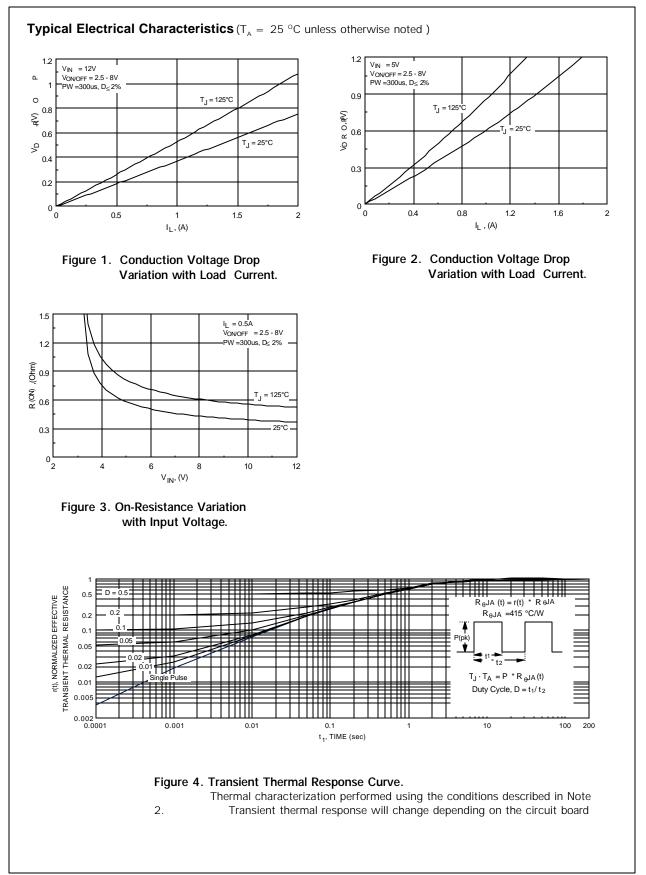
FDG6324L Load Switch Application

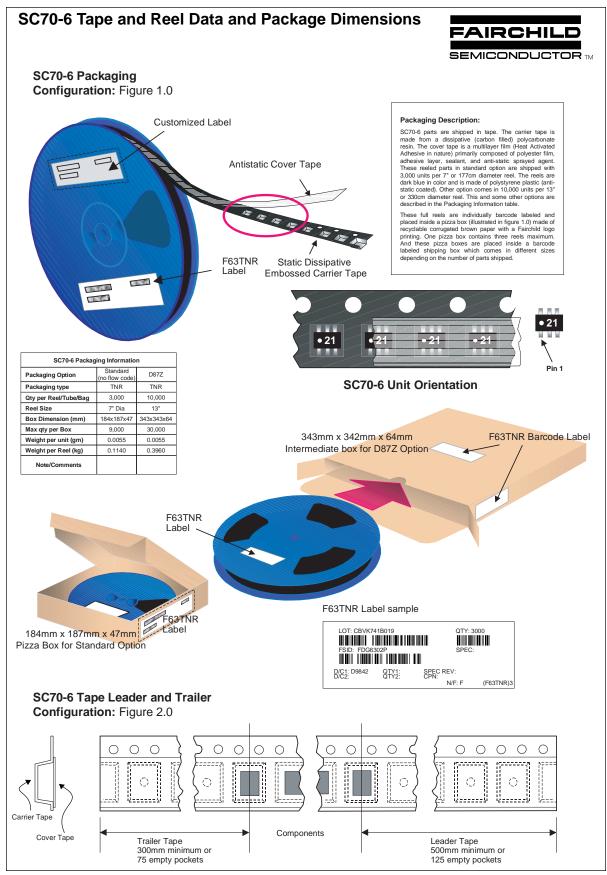


External Component Recommendation

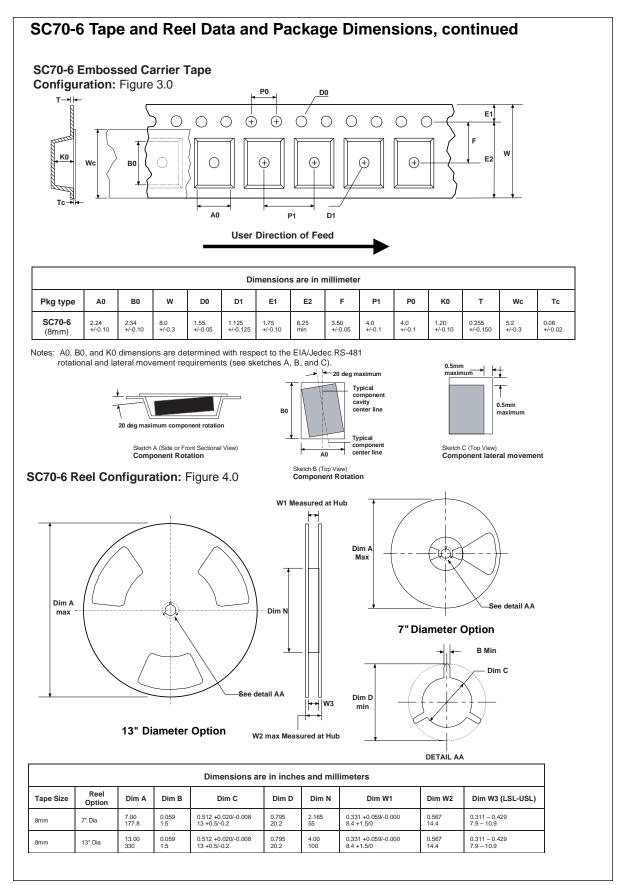
For Co \leq 1uF applications: R1 is required to turn Q2 off. R2 and C1 are optional for slew rate control. First select R2, 100 -1K Ω , for slew rate control. Then select R1 such that the ratio R1/R2 is maintained between 10-100. SPICE model (FDG6324L.MOD) available at www.fairchildsemi.com.

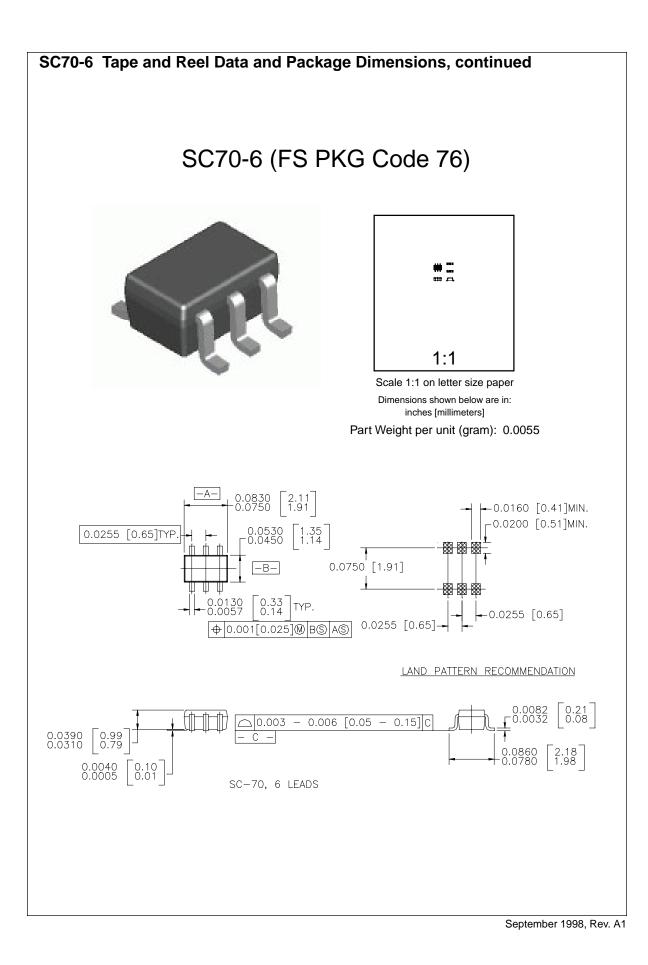
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